

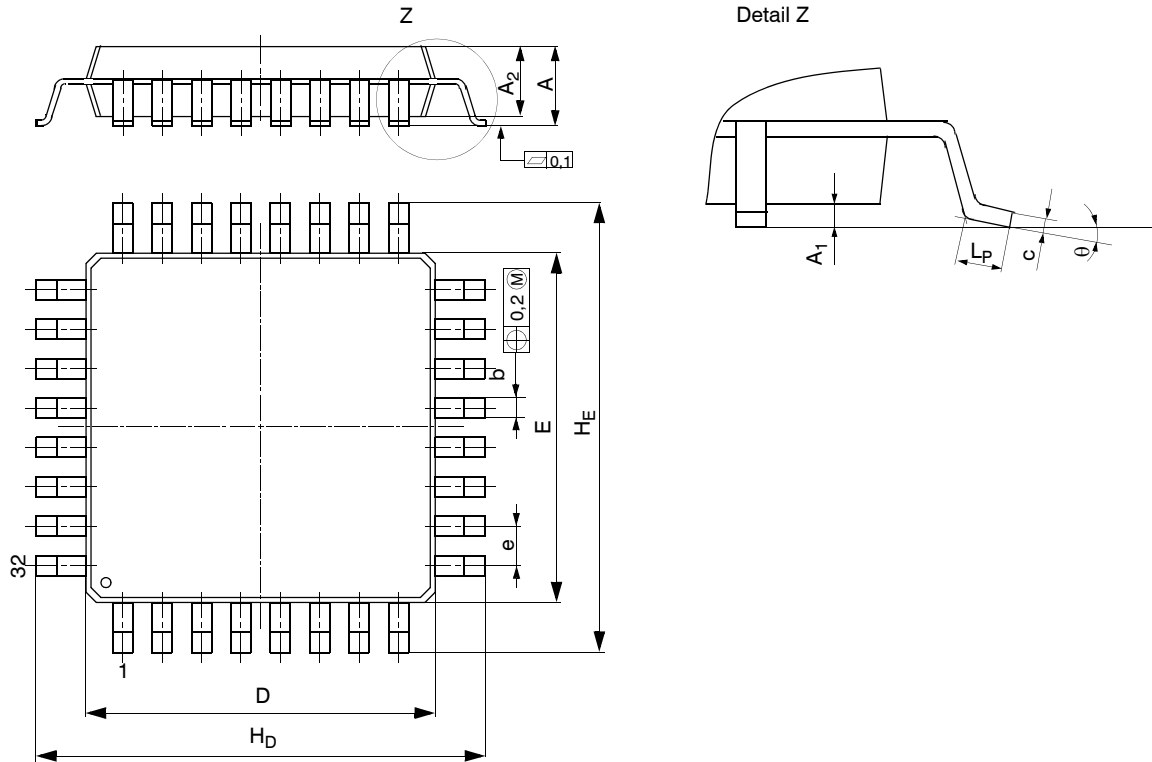

**Package LQFP32**  
 (7 x 7)

**MDS**  
**738**

 Supersedes  
 Edition 11.95

Dimensions in millimetres

Based on JEDEC JEP95: MO-136 BC

**1 Dimensions**

Dimensions of Sub-Group B1	
$e_{nom}$	0,80
$A_{max}$	1,60
$b_{Pmin}$	0,30
$b_{Pmax}$	0,45
$H_{Emin}$	8,85
$H_{Emax}$	9,15
$H_{Dmin}$	8,85
$H_{Dmax}$	9,15
$L_{Pmin}$	0,45

Dimensions of Sub-Group C1	
$A_{1min}$	0,05
$A_{1max}$	0,15
$A_{2min}$	1,35
$A_{2max}$	1,45
$c_{min}$	0,09
$c_{max}$	0,20
$D_{min}$	6,75
$D_{max}$	7,25
$E_{min}$	6,75
$E_{max}$	7,25
$\theta_{min}$	0°
$\theta_{max}$	7°

- 2 Weight**  $\leq 0,2$  g
- 3 Body Material** Low Stress Epoxy
- 4 Lead Material** FeNi-Alloy or Cu-Alloy
- 5 Lead Finish** solder plating
- 6 Lead Form** Z-bends

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